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APPLICANTS

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\*\* CONTINUING DATA \*\*\*\*\*  
*No*

\*\* FOREIGN APPLICATIONS \*\*\*\*\*  
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*yes*

IF REQUIRED, FOREIGN FILING LICENSE GRANTED  
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35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged	Examiner's Signature <i>[Signature]</i>	Initials		

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TITLE  
 Semiconductor package with build-up layers formed on chip and fabrication method of the semiconductor package

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